MOTOROLA
SEMICONDUCTOR
TECHNICAL DATA

BD806* BD808 BD810

PLASTIC HIGH POWER SILICON PNP TRANSISTOR

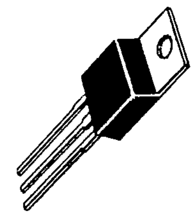
. . . designed for use in high power audio amplifiers utilizing complementary or quasi complementary circuits.

- DC Current—h_{FE} = 30 (Min) @ I_C = 2.0 Adc
- BD 806, 808, 810 are complementary with BD 805, 807, 809

10 AMPERE
POWER TRANSISTOR

PNP SILICON

45, 60, 80 VOLTS
90 WATTS



MAXIMUM RATINGS

Rating	Symbol	Type	Value	Unit
Collector-Emitter Voltage	V_{CEO}	BD806 BD808 BD810	45 60 80	Vdc
Collector-Base Voltage	V_{CBO}	BD806 BD808 BD810	55 70 80	Vdc
Emitter-Base Voltage	V_{EBO}		5	Vdc
Collector Current	I_C		10.0	Adc
Base Current	I_B		6.0	Adc
Total Device Dissipation T_C=25°C Derate above 25°C	P_D		90 720	Watts mW/°C
Operating and Storage Junction Temperature Range	T_J, T_{stg}		−55 to +150	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol		Max	Unit
Thermal Resistance, Junction to Case	θ_{JC}		1.39	°C/W

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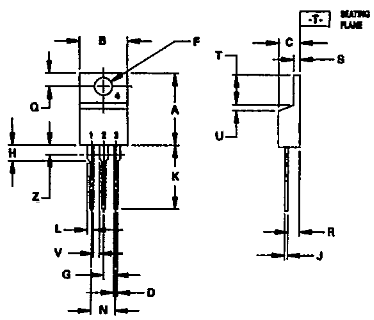
ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Type	Min	Max	Unit
Collector-Emitter Sustaining Voltage* (I_C = 0.2 Adc, I_B = 0)	BV_{CEO}*	BD806 BD808 BD810	45 60 80	– – –	Vdc
Collector Cutoff Current (V_{CB} = 55 Vdc, I_E = 0) (V_{CB} = 70 Vdc, I_E = 0) (V_{CB} = 80 Vdc, I_E = 0)	I_{CBO}	BD806 BD808 BD810	– – –	1.0 1.0 1.0	mAdc
Emitter Cutoff Current (V_{BE} = 5.0 Vdc, I_C = 0)	I_{EBO}		—	2.0	mAdc
DC current Gain (I_C = 2A, V_{CE} = 2 V) (I_C = 4A, V_{CE} = 2 V)	h_{FE}*		30 15	— —	
Collector-Emitter Saturation Voltage* (I_C = 4 Adc, I_B = 0.4 Adc)	$V_{CE(sat)}$*		—	1.1	Vdc
Base-Emitter On Voltage* (I_C = 4 Adc, V_{CE} = 2.0 Vdc)	$V_{BE(on)}$*		—	1.6	Vdc
Current-Gain-Bandwidth Product (I_C = 1.0 Adc, V_{CE} = 10 Vdc, f = 1.0 MHz)	f_T		1.5	—	MHz

* Pulse Test: Pulse Width ≤ 300 µs, Duty Cycle ≤ 2.0%.



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIM Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

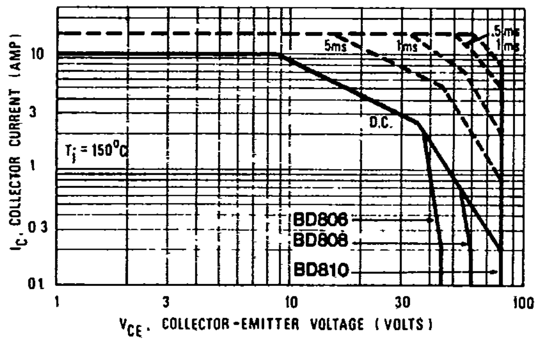
DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	14.48	15.75	0.570	0.620
B	9.66	10.28	0.380	0.405
C	4.07	4.82	0.160	0.190
D	0.64	0.88	0.025	0.035
F	3.61	3.73	0.142	0.147
G	2.42	2.66	0.095	0.105
H	2.80	3.93	0.118	0.155
J	0.46	0.71	0.018	0.028
K	12.70	14.27	0.500	0.562
L	1.15	1.39	0.045	0.055
N	4.83	5.33	0.190	0.210
Q	2.54	3.04	0.100	0.120
R	2.04	2.79	0.080	0.110
S	1.15	1.39	0.045	0.055
T	5.97	6.47	0.235	0.255
U	0.00	1.27	0.000	0.050
V	1.15	—	0.045	—
Z	—	2.04	—	0.080

STYLE 1.
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

CASE 221A-04
TO-220AB

T-33-21

FIGURE 1 – ACTIVE REGION DC SAFE OPERATING AREA



See Note 1

FIGURE 2 — POWER-TEMPERATURE DERATING CURVE

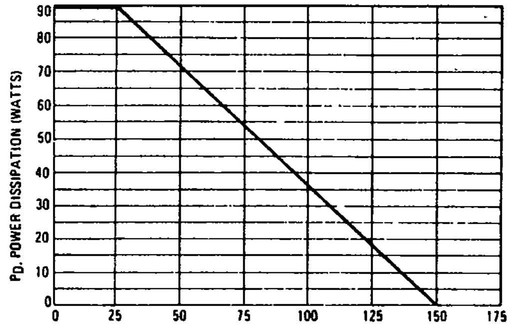


FIGURE 3 "ON" VOLTAGES

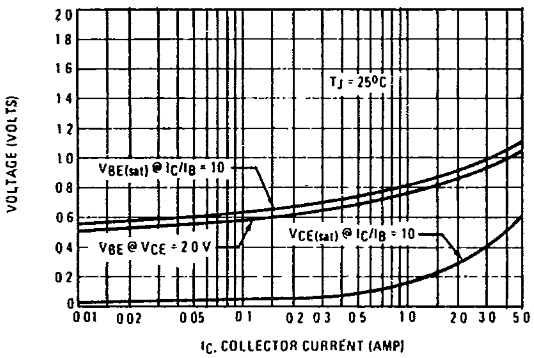


FIGURE 4 – CURRENT GAIN

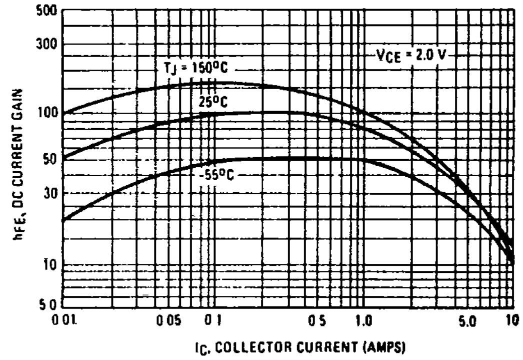
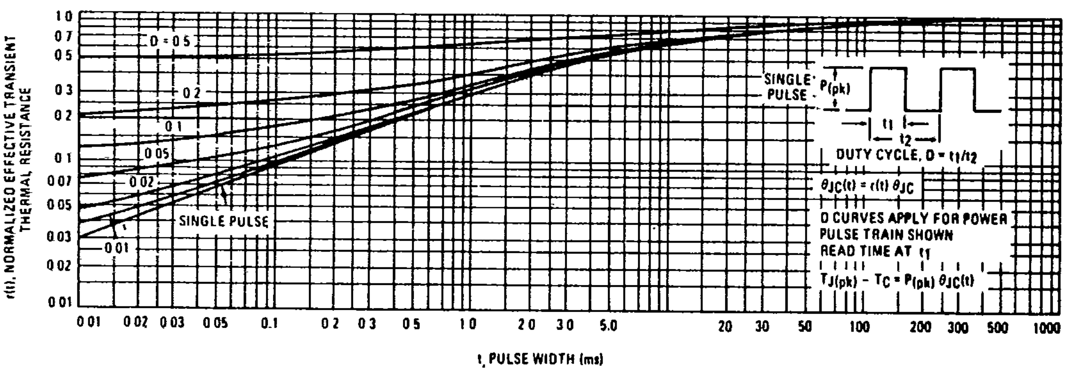


FIGURE 5 — THERMAL RESPONSE



Note 1:

There are two limitations on the power handling ability of a transistor, average junction temperature and second breakdown. Safe operating area curves indicate I_C - V_{CE} limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 1 is based on $T_{J(pk)}$ = 150°C; T_C is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150°C$. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown. (See AN-415)